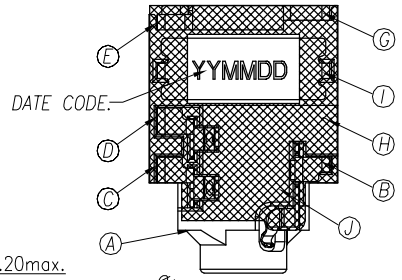
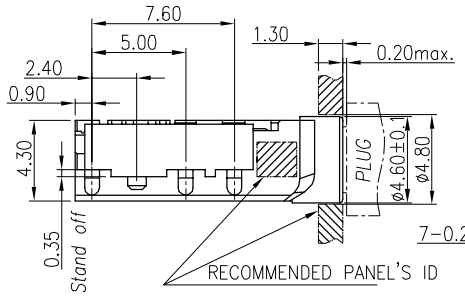
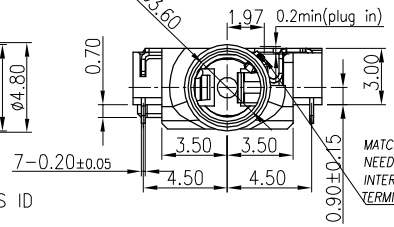
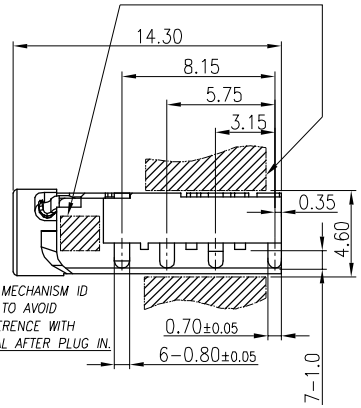
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: S160912-1A	ROBIN	2017.03.01



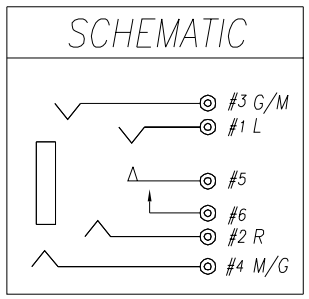


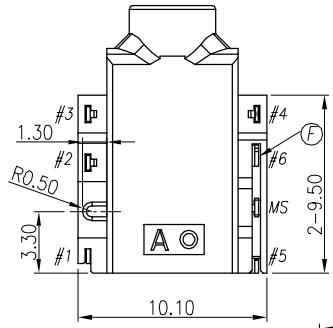


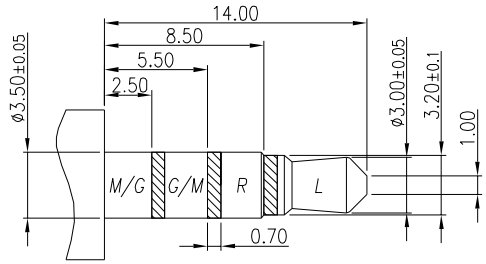


SPECIFICATIONS:

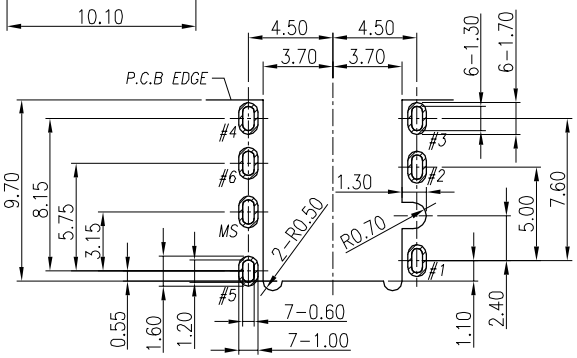
1. INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
2. CONTACT RESISTANCE: 50mΩ MAX(INITIAL).
3. INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
4. UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
5. LIFE TEST: 5,000 CYCLES MIN.
6. INSERTION FORCE: 0.3 - 3Kg.
7. WITHDRAWAL FORCE: 0.2 - 3Kg.
8. AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
9. AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
10. PACKING : TAPE & REEL.
11. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
12. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
13. HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING.







RECOMMENDED PLUG
ø3.5 4-POLE PLUG(TOL.±0.05)



RECOMMENDED PCB LAYOUT
TOP VIEW ; TOL.±0.05

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
J	MYLAR	1	T=0.10	YELLOW
I	SHELL	1	SUS304-1/2H 0.2t	Ni 60u"Min.
H	SEPARATOR	1	LCP E130i +30% GF UL 94V-0	BLACK
G	TRANSFER TERMINAL	1	CH5210-EH 0.2t	GOLD FLASH ON CONTACT AREA; GOLD FLASH ON SOLDER AREA; ALL OVER 50u" Ni.
F	MAKE TERMINAL	1	CH5210-EH 0.2t	GOLD FLASH ON CONTACT AREA; MATTE Sn80u" ON SOLDER AREA; ALL OVER 50u" Ni.
E	TIP SPRING	1	CH5210-EH 0.2t	GOLD FLASH ON CONTACT AREA; MATTE Sn80u" ON SOLDER AREA; ALL OVER 50u" Ni.
D	RING A	1	CH5210-EH 0.2t	
C	RING B	1	CH5210-EH 0.2t	
B	EARTH	1	CH5210-EH 0.2t	
A	BODY	1	PA4T+30%GF,UL94V-0	BLACK

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: X :±0.5, X.X :±0.3, X.XX :±0.2
ANGLES: X :±2°, X.X :±1°

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	3.5ø PHONE JACK			
DWN	ROBIN	PART NO. 2SJ3108-087111F		
CHKD	BRUCE	SCALE 4:1	UNIT: mm	
APVD	LUSSEN	SIZE: A3	SHEET:1 OF 1	REV: A

CUSTOMER COPY

文件編號:RD-06-043-A